

1. Record Nr.	UNINA9910783645503321
Titolo	State and society in the Second and Third Worlds [[electronic resource]] : comparative and case studies from Africa, Eurasia, Latin America, and the Middle East / / editor, Moshe Gammer
Pubbl/distr/stampa	Portland, OR, : Frank Cass, 2004
ISBN	1-135-76609-6 1-280-10394-9 0-203-31232-5
Descrizione fisica	1 online resource (201 p.)
Altri autori (Persone)	GammerM
Disciplina	320.54/0172/4
Soggetti	Nationalism Cross-cultural studies
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Most of the papers were presented at an international conference held at Tel Aviv University in April 2001.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Book Cover; Title; Contents; Contributors; Preface; Political Community and State Structures: Europe and Japan in Comparative View; A Historical-anthropological Look at Some Sociopolitical Problems of Second and Third World Countries; Informal Structures of Power (Clans) and Administration Models in the Post-Soviet and Post-colonial Worlds; Criminal Social Structures and Normative Society in Russia Today: A Growing Interaction; Peronist Nationalism and the Hispanic Heritage in Argentina; National and State Identity in Syria Traditional Monarchy and the Emergence of Modern Nationalism: The Moroccan Experience'Ulama and National Movements in the Middle East: Between Harmony and Dissent; Islamic Nationalism in Iran and Its Ideological, Military and Foreign-policy Aspects; Communities of Ideas: Blyden, Senghor and the Evolution of the Discourse Between Pan-Africanism and Islam; Oil and Tribal Politics: Changing the Guard in Abu Dhabi; The Iraqi Kurds: Hour of Power?; Index
Sommario/riassunto	The studies in this volume originated from an international conference on 'Community, Identity and the State' held at Tel Aviv University in 2001. The first two chapters examine whether modernisation, Westernisation and democratisation are identical, and whether

democracy is connected to a certain, specific type of social structure. The third examines similarities in the political, economic and social development of 'Second World' and 'Third World' countries, while the fourth discusses the relationship between criminal and 'normal' structures in Russian society. Subsequent chapters focus on na

2. Record Nr.	UNINA9910830902103321
Titolo	Interferon [[electronic resource]] : Ciba Foundation symposium dedicated to Alick Isaacs / / edited by G.E.W. Wolstenholme and Maeve O'Connor
Pubbl/distr/stampa	London, : J. & A. Churchill Ltd., 1968
ISBN	1-280-76854-1 9786613679314 0-470-71962-1 0-470-71722-X
Descrizione fisica	1 online resource (294 p.)
Collana	Novartis Foundation Symposia ; ; v.982
Altri autori (Persone)	WolstenholmeG. E. W (Gordon Ethelbert Ward) O'ConnorMaeve IsaacsAlick <1921-1967.>
Disciplina	576.64 576/.64
Soggetti	Interferon
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Note generali	"Containing 54 illustrations"--T.p. verso.
Nota di bibliografia	Includes bibliographical references and indexes.
Nota di contenuto	INTERFERON; Contents; Chairman's opening remarks; Cellular events preceding interferon formation; Discussion; The systemic induction of interferon; Discussion; Statolon, as an inducer of interferon; Discussion; Interferon induction in mouse and man with viral and non-viral stimuli; Discussion; A simple system for the mass production of human interferon: the human amniotic membrane; Discussion; General Discussion; Purification of interferons; Discussion; On the apparent heterogeneity of rabbit interferons; Discussion; Studies on the mechanism of action of interferon; Discussion

The mode of action of interferon Discussion; Studies on interferon action; Discussion; The mechanism of action of interferon; Discussion; General Discussion; Some determinants of the interferon-induced antiviral state; Discussion; Of mice and men: studies with interferon; Discussion; Effect of different carcinogenic agents on the production of interferon in tissue culture and in the animal; Discussion; The effect of interferon preparations on Friend leukemia in mice; Discussion; Group Discussion; Author Index; Subject Index

3. Record Nr.	UNINA9911020272603321
Autore	Meng Hong
Titolo	Flexible Electronic Packaging and Encapsulation Technology
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Descrizione fisica	1 online resource (379 pages)
Altri autori (Persone)	HuangWei
Disciplina	621.381046
Soggetti	Flexible electronics Electronic packaging
Lingua di pubblicazione	Inglese
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Livello bibliografico	Monografia
Nota di contenuto	Cover -- Title Page -- Copyright -- Contents -- Preface -- Chapter 1 Overview of Flexible Electronic Encapsulating Technology -- 1.1 Flexible Electronics Overview -- 1.2 Development of Flexible Electronic Encapsulating Technology -- 1.2.1 Flip Chip Process -- 1.2.2 Progress of CIFBased Flexible Electronic Encapsulating Technology -- 1.3 Encapsulating Technology of Several Important Flexible Electronic Devices -- 1.3.1 Organic LightEmitting Diode -- 1.3.2 Flexible Solar Cell Encapsulating -- 1.3.3 Flexible Amorphous Silicon Solar Cells -- 1.3.4 Flexible Perovskite Solar Cells -- 1.4 Flexible Electronic Encapsulating Materials -- 1.4.1 Selection Principle of Flexible

Electronic Encapsulating Materials -- 1.4.2 Desirable Properties of Flexible Electronic Encapsulating Materials -- 1.5 Overview of the Development of Flexible Electronic Packaging at Home and Abroad -- References -- Chapter 2 Basic Concepts Related to Flexible Electronic Packaging -- 2.1 Composition of Flexible Electronic Packaging -- 2.1.1 Flexible Substrate -- 2.1.2 Electronic Components -- 2.1.3 Crosslinked Conductive Materials -- 2.1.4 Adhesive Layer -- 2.1.5 Coating Layer -- 2.2 Flexible Electronic Packaging Structure -- 2.2.1 Curved Structures of Hard Thin Films -- 2.2.2 IslandBridge Structure -- 2.2.3 Prestrained SuperSoft Interconnect Structure -- 2.2.4 Open Grid Structure -- 2.3 Encapsulation Principle -- 2.3.1 Basic Principle of Penetration -- 2.3.2 Permeation Mechanism of Water Vapor and Gas -- 2.3.3 Barrier Performance Measurement -- 2.3.4 ThinFilm Barrier Technology for Organic Devices -- 2.3.4.1 SingleLayer Film Package -- 2.3.4.2 Multilayer Film Packaging -- 2.3.5 Film Encapsulation Mechanics -- 2.4 Packaging Technology -- 2.4.1 Local Multilayer Packaging -- 2.4.2 Multilayer Barrier Film Packaging -- 2.4.3 Online ThinFilm Encapsulation. -- 2.4.4 Atomic Layer Deposition (ALD) Encapsulation -- 2.4.5 Inkjet Packaging -- 2.4.6 Flexible Glass Packaging -- 2.5 Packaging Stability -- 2.6 Encapsulated Products -- 2.7 Chapter Summary -- References -- Chapter 3 Flexible Substrates -- 3.1 Concept and Connotation of Flexible Substrates -- 3.2 Development History of Flexible Substrates -- 3.3 Flexible Substrate Materials -- 3.3.1 Polydimethylsiloxane -- 3.3.2 Polyvinyl Alcohol -- 3.3.3 Polycarbonate -- 3.3.4 Polyester -- 3.3.5 Polyimide -- 3.3.6 Polyurethane -- 3.3.7 Parylene -- 3.3.8 Liquid Crystal Polymer -- 3.3.9 Hydrogel -- 3.4 Molding Technology of Flexible Substrate -- 3.4.1 Coating Technology -- 3.4.1.1 Dip Coating Method -- 3.4.1.2 Air Knife Coating Method -- 3.4.1.3 Scraper Coating Method -- 3.4.1.4 Rotary Coating Method -- 3.4.2 Melt Extrusion Molding -- 3.4.3 Melt Extrusion Blow Molding -- 3.4.4 Solution Tape Casting -- 3.4.5 Bidirectional Drawing Molding -- 3.4.6 Chemical Vapor Deposition -- 3.5 Performance Evaluation of Flexible Substrates -- 3.5.1 Mechanical Flexibility -- 3.5.2 Ductility -- 3.5.3 Adhesive Property -- 3.5.4 Barrier Property -- 3.5.5 Electrical Property -- 3.5.6 Chemical Stability -- 3.5.7 Dimensional Stability -- 3.5.8 Surface Smoothness and Thickness Uniformity -- 3.5.9 Optical Clarity (Transmittance) -- 3.5.10 Biocompatibility -- 3.5.11 Bioabsorbability -- 3.6 Application of Flexible Substrates -- 3.6.1 Flexible Display Substrates -- 3.6.2 Flexible Electrode Substrates -- 3.6.3 Flexible Sensing Substrates -- 3.7 Development Trend of Flexible Substrates -- 3.7.1 Intelligent and Functional Flexible Substrates -- 3.7.2 Green Degradable Flexible Substrates -- 3.7.3 Optimization of Interface Compatibility of Flexible Substrates -- References -- Chapter 4 Test Methods -- 4.1 Sealing Test -- 4.1.1 Direct Diffusion Method -- 4.1.1.1 Weight Cup Test. -- 4.1.1.2 Differential Pressure Method -- 4.1.1.3 Balancing Method -- 4.1.1.4 Tunable Diode Laser Absorption Spectrometry -- 4.1.1.5 Isotope Labeling Mass Spectrometry -- 4.1.2 Indirect Optical Method -- 4.1.3 Indirect Electrical Method -- 4.1.3.1 Calcium Electrical Test -- 4.1.3.2 Dielectric Measurement Method -- 4.1.4 Indirect Electrochemical Method -- 4.1.4.1 Electrochemical Impedance Spectroscopy (EIS) -- 4.1.4.2 Leakage Current Monitoring Method (LCM) -- 4.1.4.3 Linear Scanning Voltammetry (LSV) -- 4.1.5 Indirect Electromechanical Method -- 4.2 Bending Test -- 4.2.1 Static Bending and Dynamic Bending -- 4.2.2 ThreePoint Bending and FourPoint Bending -- 4.2.3 Push Bending and Roll Bending -- 4.2.3.1 Push Bending -- 4.2.3.2 Rolling Bend -- 4.3 Mechanical Performance Testing

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Physical Characteristics Related Terms -- 8.1.2.4 Terms Related to Construction Elements -- 8.1.2.5 Symbols Related to Performances and Specifications -- 8.1.2.6 Terms Related to the Production Process -- 8.1.3 Alphabetic Symbols (Quantity Symbols/Unit Symbols) -- 8.1.3.1 Classification -- 8.1.3.2 Symbols -- 8.2 Mechanical Test Method (Deformation Test) -- 8.2.1 Cyclic Bending Test -- 8.2.1.1 Purpose -- 8.2.1.2 Testing Device -- 8.2.1.3 Test Procedure -- 8.2.1.4 Test Conditions and Reports -- 8.2.2 Static Bending Test -- 8.2.2.1 Purpose -- 8.2.2.2 Testing Device -- 8.2.2.3 Test Steps -- 8.2.2.4 Test Conditions and Reports -- 8.2.3 Combined Bending Test -- 8.2.3.1 Purpose -- 8.2.3.2 Testing Device -- 8.2.3.3 Test Procedure -- 8.2.3.4 Test Conditions and Reports -- 8.2.4 Rolling Test -- 8.2.4.1 Purpose -- 8.2.4.2 Testing Device -- 8.2.4.3 Test Procedure -- 8.2.4.4 Test Conditions and Reports -- 8.2.5 Static Rolling Test -- 8.2.5.1 Purpose -- 8.2.5.2 Testing Device. 8.2.5.3 Test Procedure.

Sommario/riassunto

This book provides a comprehensive exploration of flexible electronic packaging and encapsulation technology, offering insights into its development, basic concepts, and applications. The editors, Hong Meng and Wei Huang, compile contributions from various experts, detailing the historical development and key components of flexible electronics. The book covers topics such as flexible substrates, test methods, and the application of flexible electronic packaging in various industries including healthcare and photovoltaics. It is aimed at researchers, engineers, and students in the field of electronics who are interested in the technological advancements and commercial potentials of flexible electronics.
